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PIC18F24/25Q10

28-Pin, Low-Power, High-Performance Microcontrollers

Description

PIC18F24/25Q10 microcontrollers feature Analog, Core Independent, and Communication Peripherals for a wide range of general purpose and low-power applications. These 28 -pin devices are equipped with a 10-bit ADC with Computation (ADC^2) automating Capacitive Voltage Divider (CVD) techniques for advanced touch sensing, averaging, filtering, oversampling and performing automatic threshold comparisons. They also offer a set of Core Independent Peripherals such as Complementary Waveform Generator (CWG), Windowed Watchdog Timer (WWDT), Cyclic Redundancy Check (CRC)/Memory Scan, Zero-Cross Detect (ZCD), and Peripheral Pin Select (PPS), providing for increased design flexibility and lower system cost.

Core Features

- C Compiler Optimized RISC Architecture
- Operating Speed:
  - DC – 64 MHz clock input over the full V_{DD} range
  - 62.5 ns minimum instruction cycle
- Programmable 2-Level Interrupt Priority
- 31-Level Deep Hardware Stack
- Three 8-Bit Timers (TMR2/4/6) with Hardware Limit Timer (HLT)
- Four 16-Bit Timers (TMR0/1/3/5)
- Low-Current Power-on Reset (POR)
- Power-up Timer (PWRT)
- Brown-out Reset (BOR)
- Low-Power BOR (LPBOR) Option
- Windowed Watchdog Timer (WWDT):
  - Watchdog Reset on too long or too short interval between watchdog clear events
  - Variable prescaler selection
  - Variable window size selection
  - All sources configurable in hardware or software

Memory

- Up to 32K Bytes Program Flash Memory
- Up to 2048 Bytes Data SRAM Memory
- 256 Bytes Data EEPROM
- Programmable Code Protection

- Direct, Indirect and Relative Addressing modes

Operating Characteristics

- Operating Voltage Range:
  - 1.8V to 5.5V
- Temperature Range:
  - Industrial: -40°C to 85°C
  - Extended: -40°C to 125°C

Power-Saving Operation Modes

- Doze: CPU and Peripherals Running at Different Cycle Rates (typically CPU is lower)
- Idle: CPU Halted While Peripherals Operate
- Sleep: Lowest Power Consumption
- Peripheral Module Disable (PMD):
  - Ability to selectively disable hardware module to minimize active power consumption of unused peripherals
- Extreme Low-Power mode (XLP)
  - Sleep: 500 nA typical @ 1.8V
  - Sleep and Watchdog Timer: 900 nA typical @ 1.8V

Digital Peripherals

- Complementary Waveform Generator (CWG):
  - Rising and falling edge dead-band control
  - Full-bridge, half-bridge, 1-channel drive
  - Multiple signal sources
- Capture/Compare/PWM (CCP) modules:
  - Two CCPs
  - 16-bit resolution for Capture/Compare modes
  - 10-bit resolution for PWM mode
- 10-Bit Pulse-Width Modulators (PWM):
  - Two 10-bit PWMs
- Serial Communications:
  - One Enhanced USART (EUSART) with Auto-Baud Detect, Auto-wake-up on Start. RS-232, RS-485, LIN compatible
  - SPI
  - I^2C, SMBus and PMBus™ compatible
- Up to 25 I/O Pins and One Input Pin:
  - Individually programmable pull-ups
  - Slew rate control
  - Interrupt-on-change on all pins
  - Input level selection control
- Programmable CRC with Memory Scan:

  - Reliable data/program memory monitoring for Fail-Safe operation (e.g., Class B)
  - Calculate CRC over any portion of Flash or EEPROM
  - High-speed or background operation
- Hardware Limit Timer (TMR2/4/6+HLT):
  - Hardware monitoring and Fault detection
- Peripheral Pin Select (PPS):
  - Enables pin mapping of digital I/O
- Data Signal Modulator (DSM)

Analog Peripherals

- 10-Bit Analog-to-Digital Converter with Computation (ADC^2):
  - 24 external channels
  - Conversion available during sleep
  - Four internal analog channels
  - Internal and external trigger options
  - Automated math functions on input signals:
    - Averaging, filter calculations, oversampling and threshold comparison
  - 8-bit hardware acquisition timer
- Hardware Capacitive Voltage Divider (CVD) Support:
  - 8-bit precharge timer
  - Adjustable sample and hold capacitor array
  - Guard ring digital output drive
- Zero-Cross Detect (ZCD):
  - Detect when AC signal on pin crosses ground
- 5-Bit Digital-to-Analog Converter (DAC):
  - Output available externally
  - Programmable 5-bit voltage (% of V_{DD},[V_{Ref+} - V_{Ref-}], FVR)
  - Internal connections to comparators and ADC
- Two Comparators (CMP):
  - Four external inputs
  - External output via PPS
- Fixed Voltage Reference (FVR) Module:
  - 1.024V, 2.048V and 4.096V output levels
  - Two buffered outputs: One for DAC/CMP and one for ADC

Clocking Structure

- High-Precision Internal Oscillator Block (HFINTOSC):
  - Selectable frequencies up to 64 MHz
  - ±1% at calibration
- 32 kHz Low-Power Internal Oscillator (LFINTOSC)
- External 32 kHz Crystal Oscillator (SOSC)
- External High-frequency Oscillator Block:
  - Three crystal/resonator modes

  - Digital Clock Input mode
  - 4x PLL with external sources
- Fail-Safe Clock Monitor:
  - Allows for safe shutdown if external clock stops
- Oscillator Start-up Timer (OST)

Programming/Debug Features

- In-Circuit Serial Programming™ (ICSP™) via Two Pins
- In-Circuit Debug (ICD) with Three Breakpoints via Two Pins
- Debug Integrated On-Chip

PIC18F24/25Q10 Family Types

Table 1. Devices included in this data sheet

Device	Program Memory Flash (bytes)	Data SRAM (bytes)	Data EEPROM (bytes)	I/O Pins	16-bit Timers	Comparators	10-bit ADC² with Computation (ch)	5-bit DAC	Zero-Cross Detect	CCP/10-bit PWM	CWG	CLC	Low Voltage Detect (LVD)	8-bit TMR with HLT	Windowed Watchdog Timer	CRC with Memory Scan	EUSART	I²C/SPI	PPS	Peripheral Module Disable	Temperature Indicator	Debug(1)
PIC18F24Q10	16k	1024	256	25	4	2	24	1	1	2/2	1	0	1	3	Y	Y	1	1	Y	Y	Y	I
PIC18F25Q10	32k	2048	256	25	4	2	24	1	1	2/2	1	0	1	3	Y	Y	1	1	Y	Y	Y	I

Table 2. Devices not included in this data sheet

Device	Program Memory Flash (bytes)	Data SRAM (bytes)	Data EEPROM (bytes)	I/O Pins	16-bit Timers	Comparators	10-bit ADC² with Computation (ch)	5-bit DAC	Zero-Cross Detect	CCP/10-bit PWM	CWG	CLC	Low Voltage Detect (LVD)	8-bit TMR with HLT	Windowed Watchdog Timer	CRC with Memory Scan	EUSART	I²C/SPI	PPS	Peripheral Module Disable	Temperature Indicator	Debug(1)
PIC18F26Q10	64k	3615	1024	25	4	2	24	1	1	2/2	1	8	1	3	Y	Y	2	2	Y	Y	Y	I
PIC18F27Q10	128k	3615	1024	25	4	2	24	1	1	2/2	1	8	1	3	Y	Y	2	2	Y	Y	Y	I
PIC18F45Q10	32k	2048	256	36	4	2	35	1	1	2/2	1	8	1	3	Y	Y	2	2	Y	Y	Y	I
PIC18F46Q10	64k	3615	1024	36	4	2	35	1	1	2/2	1	8	1	3	Y	Y	2	2	Y	Y	Y	I
PIC18F47Q10	128k	3615	1024	36	4	2	35	1	1	2/2	1	8	1	3	Y	Y	2	2	Y	Y	Y	I

Note: Debugging Methods: (I) – Integrated on Chip.

Data Sheet Index:

1. DS40001996 Data Sheet, 28/40-Pin, 8-bit Flash Microcontrollers
2. DS(TBD) Data Sheet, 28/40-Pin, 8-bit Flash Microcontrollers

Packages

Important: For other small form-factor package availability and marking information, visit http://www.microchip.com/packaging or contact your local Microchip sales office.

Packages	SPDIP (SP)	SOIC (SO)	SSOP (SS)	QFN (ML) (6x6x0.9)	VQFN (STX) (4x4x1)	TQFP (PT)	PDIP (P)	VQFN (NHX) (5x5x0.9)	QFN (ML) (8x8)
PIC18F24Q10	•	•	•	•	•				
PIC18F25Q10	•	•	•	•	•				

Important: Pin details are subject to change.

Pin Diagrams

Figure 1. 28-pin SPDIP, SSOP, SOIC

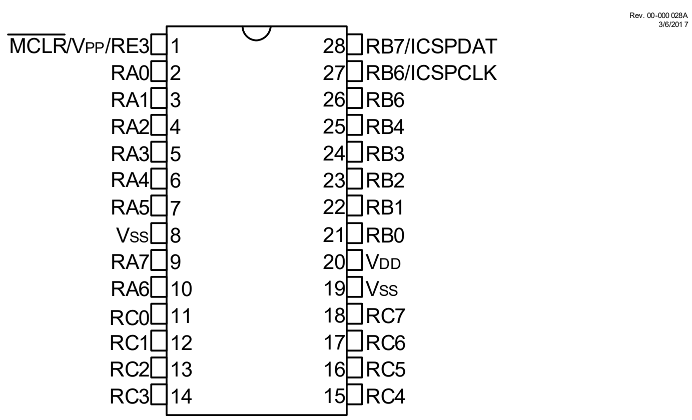
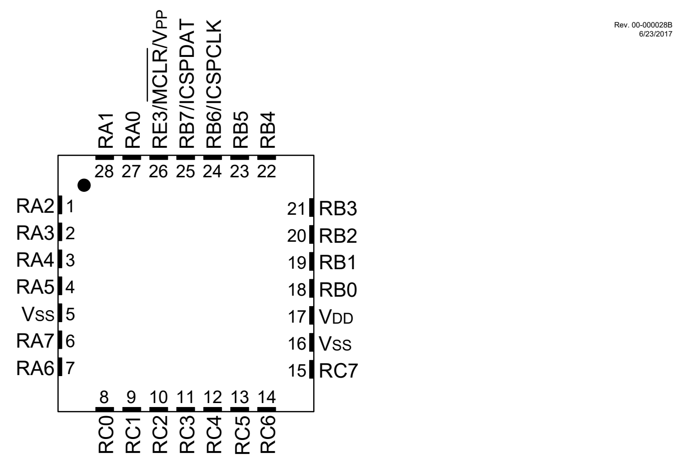


Figure 2. 28-pin QFN, VQFN



Note: It is recommended that the exposed bottom pad be connected to V_{SS}, however it must not be the only V_{SS} connection to the device.

Pin Allocation Tables

Table 1. 28-Pin Allocation Table

I/O(2)	28-Pin SPDIP, SOIC, SSOP	28-Pin (V)QFN	A/D	Reference	Comparator	Timers	CCP	CWG	ZCD	Interrupt	EUSART	DSM	MSSP	Pull-up	Basic
RA0	2	27	ANA0	—	C1IN0- C2IN0-	—	—	—	—	IOCA0	—	—	—	Y	—
RA1	3	28	ANA1	—	C1IN1- C2IN1-	—	—	—	—	IOCA1	—	—	—	Y	—
RA2	4	1	ANA2	DAC1OUT1 Vref- (DAC) Vref- (ADC)	C1IN0+ C2IN0+	—	—	—	—	IOCA2	—	—	—	Y	—
RA3	5	2	ANA3	Vref+ (DAC) Vref+ (ADC)	C1IN1+	—	—	—	—	IOCA3	—	MDCARL(1)	—	Y	—
RA4	6	3	ANA4	—	—	T0CKI(1)	—	—	—	IOCA4	—	MDCARH(1)	—	Y	—
RA5	7	4	ANA5	—	—	—	—	—	—	IOCA5	—	MDSRC(1)	$\overline{SS1}$(1)	Y	—
RA6	10	7	ANA6	—	—	—	—	—	—	IOCA6	—	—	—	Y	CLKOUT OSC2
RA7	9	6	ANA7	—	—	—	—	—	—	IOCA7	—	—	—	Y	OSC1 CLKIN
RB0	21	18	ANB0	—	C2IN1+	—	—	CWG1(1)	ZCDIN	IOCB0 INT0(1)	—	—	—	Y	—
RB1	22	19	ANB1	—	C1IN3- C2IN3-	—	—	—	—	IOCB1 INT1(1)	—	—	—	Y	—
RB2	23	20	ANB2	—	—	—	—	—	—	IOCB2 INT2(1)	—	—	—	Y	—

I/O(2)	28-Pin SPDIP, SOIC, SSOP	28-Pin (V)QFN	A/D	Reference	Comparator	Timers	CCP	CWG	ZCD	Interrupt	EUSART	DSM	MSSP	Pull-up	Basic
RB3	24	21	ANB3	—	C1IN2- C2IN2-	—	—	—	—	IOCB3	—	—	—	Y	—
RB4	25	22	ANB4	—	—	T5G(1)	—	—	—	IOCB4	—	—	—	Y	—
RB5	26	23	ANB5	—	—	T1G(1)	—	—	—	IOCB5	—	—	—	Y	—
RB6	27	24	ANB6	—	—	—	—	—	—	IOCB6	—	—	—	Y	ICSPCLK
RB7	28	25	ANB7	DAC1OUT2	—	T6IN(1)	—	—	—	IOCB7	—	—	—	Y	ICSPDAT
RC0	11	8	ANC0	—	—	T1CKI(1) T3CKI(1) T3G(1)	—	—	—	IOCC0	—	—	—	Y	SOSCO
RC1	12	9	ANC1	—	—	—	CCP2(1)	—	—	IOCC1	—	—	—	Y	SOSCIN SOSCI
RC2	13	10	ANC2	—	—	T5CKI(1)	CCP1(1)	—	—	IOCC2	—	—	—	Y	—
RC3	14	11	ANC3	—	—	T2IN(1)	—	—	—	IOCC3	—	—	SCK1(1) SCL1(3,4)	Y	—
RC4	15	12	ANC4	—	—	—	—	—	—	IOCC4	—	—	SDI1(1) SDA1(3,4)	Y	—
RC5	16	13	ANC5	—	—	T4IN(1)	—	—	—	IOCC5	—	—	—	Y	—
RC6	17	14	ANC6	—	—	—	—	—	—	IOCC6	CK1(1,3)	—	—	Y	—
RC7	18	15	ANC7	—	—	—	—	—	—	IOCC7	RX1/ DT1(1,3)	—	—	Y	—
RE3	1	26	—	—	—	—	—	—	—	IOCE3	—	—	—	Y	Vpp/$\overline{\text{MCLR}}$
V_{SS}	19	16	—	—	—	—	—	—	—	—	—	—	—	—	V_{SS}
V_{DD}	20	17	—	—	—	—	—	—	—	—	—	—	—	—	V_{DD}
V_{SS}	8	5	—	—	—	—	—	—	—	—	—	—	—	—	V_{SS}
OUT(2)	—	—	ADGRDA ADGRDB	—	C1OUT C2OUT	TMR0	CCP1 CCP2 PWM3 PWM4	CWG1A CWG1B CWG1C CWG1D	—	—	TX1/ CK1(3) DT1(3)	DSM	SDO1 SCK1	—	—

Note:

1. This is a PPS remappable input signal. The input function may be moved from the default location shown to one of several other PORTx pins. Refer to the peripheral input selection table for details on which port pins may be used for this signal.
2. All output signals shown in this row are PPS remappable. These signals may be mapped to output onto one of several PORTx pin options as described in the peripheral output selection table.
3. This is a bidirectional signal. For normal module operation, the firmware should map this signal to the same pin in both the PPS input and PPS output registers.
4. These pins are configured for I^{2}C logic levels; The SCLx/SDAx signals may be assigned to any of these pins. PPS assignments to the other pins (e.g., RB1) will operate, but input logic levels will be standard TTL/ST as selected by the INLVL register, instead of the I^{2}C specific or SMBus input buffer thresholds.

Table of Contents

1. Device Overview

This document contains device specific information for the following devices:

•	PIC18F24Q10
•	PIC18F25Q10

This family offers the advantages of all PIC18 microcontrollers – namely, high computational performance at an economical price – with the addition of high-endurance program Flash memory. In addition to these features, the PIC18F24/25Q10 family introduces design enhancements that make these microcontrollers a logical choice for many high-performance, power sensitive applications.

1.1 New Core Features

1.1.1 Low-Power Technology

All of the devices in the PIC18F24/25Q10 family incorporate a range of features that can significantly reduce power consumption during operation. Key items include:

- Alternate Run Modes: By clocking the microcontroller from the secondary oscillator or the internal oscillator block, power consumption during code execution can be reduced by as much as 90%.
- Multiple Idle Modes: The controller can also run with its CPU core disabled but the peripherals still active. In these states, power consumption can be reduced even further, to as little as 4% of normal operation requirements.
- On-the-fly Mode Switching: The power-managed modes are invoked by user code during operation, allowing the user to incorporate power-saving ideas into their application's software design.
- Peripheral Module Disable: Modules that are not being used in the code can be selectively disabled using the PMD module. This further reduces the power consumption.

1.1.2 Multiple Oscillator Options and Features

All of the devices in the PIC18F24/25Q10family offer several different oscillator options. The PIC18F24/25Q10 family can be clocked from several different sources:

- HFINTOSC
  – 1-64 MHz precision digitally controlled internal oscillator
- LFINTOSC
  – 31 kHz internal oscillator
- EXTOSC
  – External clock (EC)
  – Low-power oscillator (LP)
  – Medium-power oscillator (XT)
  – High-power oscillator (HS)
- SOSC
  – Secondary oscillator circuit optimized for 32 kHz clock crystals
- A Phase Lock Loop (PLL) frequency multiplier (4x) is available to the External Oscillator modes enabling clock speeds of up to 64 MHz

- Fail-Safe Clock Monitor: This option constantly monitors the main clock source against a reference signal provided by the LFINTOSC. If a clock failure occurs, the controller is switched to the internal oscillator block, allowing for continued operation or a safe application shutdown.

1.2 Other Special Features

- Memory Endurance: The Flash cells for both program memory and data EEPROM are rated to last for many thousands of erase/write cycles – up to 10K for program memory and 100K for EEPROM. Data retention without refresh is conservatively estimated to be greater than 40 years.
- Self-programmability: These devices can write to their own program memory spaces under internal software control. By using a boot loader routine located in the protected Boot Block at the top of program memory, it becomes possible to create an application that can update itself in the field.
- Extended Instruction Set: The PIC18F24/25Q10 family includes an optional extension to the PIC18 instruction set, which adds eight new instructions and an Indexed Addressing mode. This extension, enabled as a device configuration option, has been specifically designed to optimize re-entrant application code originally developed in high-level languages, such as C.
- Enhanced Peripheral Pin Select: The Peripheral Pin Select (PPS) module connects peripheral inputs and outputs to the device I/O pins. Only digital signals are included in the selections. All analog inputs and outputs remain fixed to their assigned pins.
- Enhanced Addressable EUSART: This serial communication module is capable of standard RS-232 operation and provides support for the LIN bus protocol. Other enhancements include automatic baud rate detection and a 16-bit Baud Rate Generator for improved resolution. When the microcontroller is using the internal oscillator block, the EUSART provides stable operation for applications that talk to the outside world without using an external crystal (or its accompanying power requirement).
- 10-bit A/D Converter with Computation: This module incorporates programmable acquisition time, allowing for a channel to be selected and a conversion to be initiated without waiting for a sampling period and thus, reduce code overhead. It has a new module called ADC^2 with computation features, which provides a digital filter and threshold interrupt functions.
- Windowed Watchdog Timer (WWDT):
  – Timer monitoring of overflow and underflow events
  – Variable prescaler selection
  – Variable window size selection
  – All sources configurable in hardware or software

1.3 Details on Individual Family Members

Devices in the PIC18F24/25Q10 family are available in 28-pin packages. The block diagram for this device is shown in Figure 1-1.

The devices have the following differences:

1. Program Flash Memory
2. Data Memory SRAM
3. Data Memory EEPROM
4. A/D channels
5. I/O ports
6. Enhanced USART

7. Input Voltage Range/Power Consumption

All other features for devices in this family are identical. These are summarized in the following Device Features table.

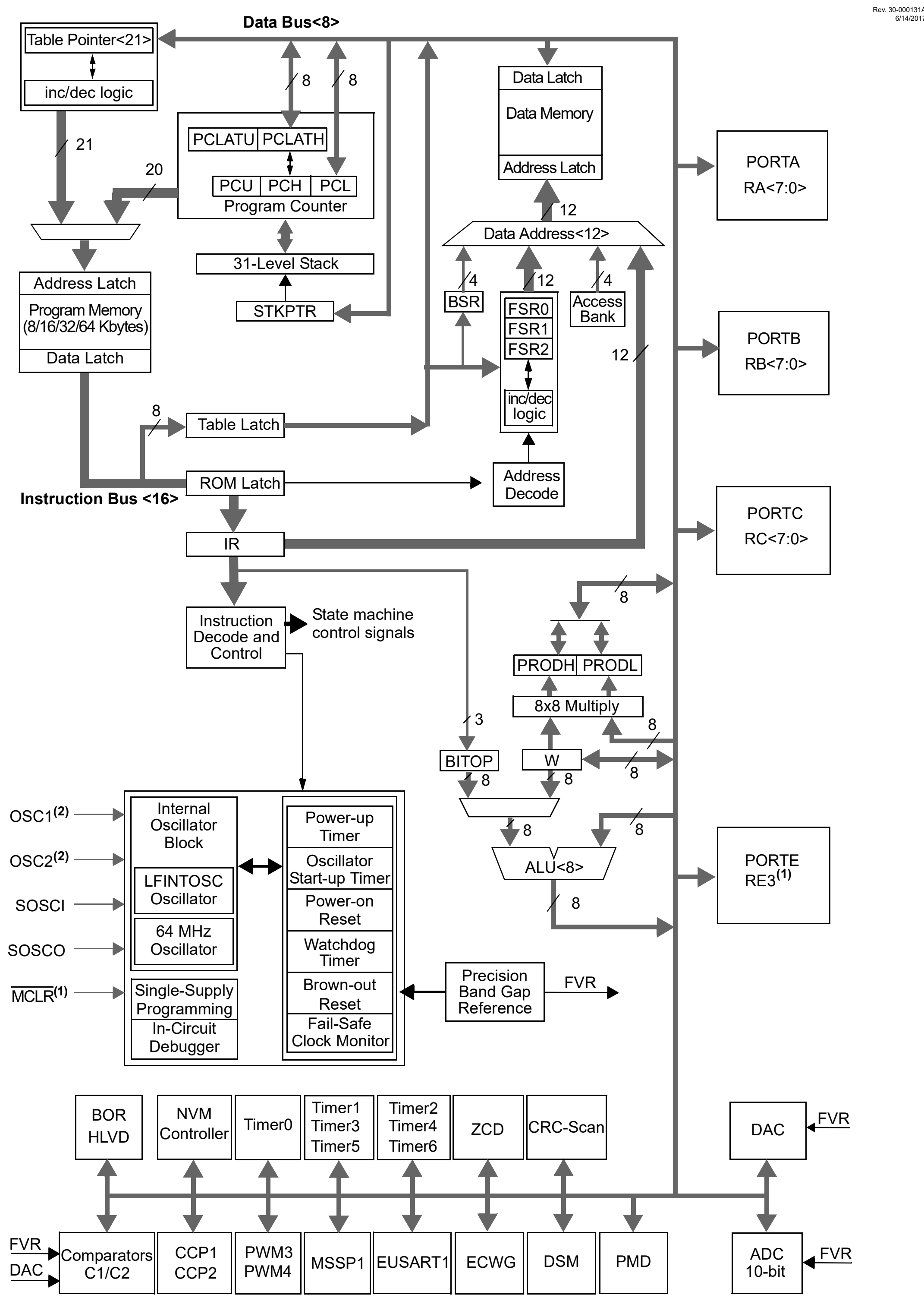
The pinouts for all devices are listed in the pin summary tables.

Table 1-1. Device Features

Features	PIC18F24Q10	PIC18F25Q10
Program Memory (Bytes)	16384	32768
Program Memory (Instructions)	8192	16384
Data Memory (Bytes)	1024	2048
Data EEPROM Memory (Bytes)	256	256
I/O Ports	A,B,C,E(1)	A,B,C,E(1)
Capture/Compare/PWM Modules (CCP)	2	2
10-Bit Pulse-Width Modulator (PWM)	2	2
10-Bit Analog-to-Digital Module (ADC^2) with Computation Accelerator	4 internal 24 external	4 internal 24 external
Packages	28-pin SPDIP 28-pin SOIC 28-pin SSOP 28-pin QFN 28-pin UQFN	28-pin SPDIP 28-pin SOIC 28-pin SSOP 28-pin QFN 28-pin UQFN
Interrupt Sources	36	
Timers (16-/8-bit)	4/3	
Serial Communications	1 MSSP, 1 EUSART	
Enhanced Complementary Waveform Generator (ECWG)	1	
Zero-Cross Detect (ZCD)	1	
Data Signal Modulator (DSM)	1	
Peripheral Pin Select (PPS)	Yes	
Peripheral Module Disable (PMD)	Yes	
16-bit CRC with NVMSCAN	Yes	
Programmable High/Low-Voltage Detect (HLVD)	Yes	
Programmable Brown-out Reset (BOR)	Yes	
Resets (and Delays)	POR, BOR,	

Features	PIC18F24Q10	PIC18F25Q10
	RESET Instruction, Stack Overflow, Stack Underflow (PWRT, OST), $\overline{\text{MCLR}}$, WDT	
Instruction Set	75 Instructions; 83 with Extended Instruction Set enabled	
Operating Frequency	DC – 64 MHz	
Note 1: PORTE contains the single RE3 read-only bit.		

Figure 1-1. PIC18F24/25Q10 Family Block Diagram



Note
1: RE3 is only available when $\overline{\text{MCLR}}$ functionality is disabled.
2: OSC1/CLKIN and OSC2/CLKOUT are only available in select oscillator modes.

1.4 Register and Bit naming conventions

1.4.1 Register Names

When there are multiple instances of the same peripheral in a device, the peripheral control registers will be depicted as the concatenation of a peripheral identifier, peripheral instance, and control identifier. The control registers section will show just one instance of all the register names with an 'x' in the place of the peripheral instance number. This naming convention may also be applied to peripherals when there is only one instance of that peripheral in the device to maintain compatibility with other devices in the family that contain more than one.

1.4.2 Bit Names

There are two variants for bit names:

- Short name: Bit function abbreviation
- Long name: Peripheral abbreviation + short name

1.4.2.1 Short Bit Names

Short bit names are an abbreviation for the bit function. For example, some peripherals are enabled with the EN bit. The bit names shown in the registers are the short name variant.

Short bit names are useful when accessing bits in C programs. The general format for accessing bits by the short name is RegisterNamebits.ShortName. For example, the enable bit, EN, in the CM1CON0 register can be set in C programs with the instruction `CM1CON0bits.EN = 1`.

Short names are generally not useful in assembly programs because the same name may be used by different peripherals in different bit positions. When this occurs, during the include file generation, all instances of that short bit name are appended with an underscore plus the name of the register in which the bit resides to avoid naming contentions.

1.4.2.2 Long Bit Names

Long bit names are constructed by adding a peripheral abbreviation prefix to the short name. The prefix is unique to the peripheral, thereby making every long bit name unique. The long bit name for the COG1 enable bit is the COG1 prefix, G1, appended with the enable bit short name, EN, resulting in the unique bit name G1EN.

Long bit names are useful in both C and assembly programs. For example, in C the COG1CON0 enable bit can be set with the `G1EN = 1` instruction. In assembly, this bit can be set with the `BSF COG1CON0,G1EN` instruction.

1.4.2.3 Bit Fields

Bit fields are two or more adjacent bits in the same register. Bit fields adhere only to the short bit naming convention. For example, the three Least Significant bits of the COG1CON0 register contain the mode control bits. The short name for this field is MD. There is no long bit name variant. Bit field access is only possible in C programs. The following example demonstrates a C program instruction for setting the COG1 to the Push-Pull mode:

COG1CON0bits.MD = 0x5;

Individual bits in a bit field can also be accessed with long and short bit names. Each bit is the field name appended with the number of the bit position within the field. For example, the Most Significant mode bit has the short bit name MD2 and the long bit name is G1MD2. The following two examples demonstrate assembly program sequences for setting the COG1 to Push-Pull mode:

Example 1:

```
MOVLW  ~(1<<G1MD1)
ANDWF  COG1CON0,F
MOVLW  1<<G1MD2 | 1<<G1MD0
IORWF  COG1CON0,F
```

Example 2:

```
BSF    COG1CON0,G1MD2
BCF    COG1CON0,G1MD1
BSF    COG1CON0,G1MD0
```

1.4.3 Register and Bit Naming Exceptions

1.4.3.1 Status, Interrupt, and Mirror Bits

Status, interrupt enables, interrupt flags, and mirror bits are contained in registers that span more than one peripheral. In these cases, the bit name shown is unique so there is no prefix or short name variant.

1.4.3.2 Legacy Peripherals

There are some peripherals that do not strictly adhere to these naming conventions. Peripherals that have existed for many years and are present in almost every device are the exceptions. These exceptions were necessary to limit the adverse impact of the new conventions on legacy code. Peripherals that do adhere to the new convention will include a table in the registers section indicating the long name prefix for each peripheral instance. Peripherals that fall into the exception category will not have this table. These peripherals include, but are not limited to the following:

- EUSART
- MSSP

1.5 Register Legend

The table below describes the conventions for bit types and bit Reset values used in the current data sheet.

Table 1-2. Register Legend

Value	Description
RO	Read-only bit
W	Writable bit
U	Unimplemented bit, read as ‘0’
P	Programmable bit
‘1’	Bit is set
‘0’	Bit is cleared
x	Bit is unknown
u	Bit is unchanged
-n/n	Value at POR and BOR/Value at all other Resets
q	Reset Value is determined by hardware

Value	Description
`f`	Reset Value is determined by fuse setting
`g`	Reset Value at POR for PPS re-mappable signals

2. Guidelines for Getting Started with PIC18F24/25Q10 Microcontrollers

2.1 Basic Connection Requirements

Getting started with the PIC18F24/25Q10 family of 8-bit microcontrollers requires attention to a minimal set of device pin connections before proceeding with development.

The following pins must always be connected:

- All V_{DD} and V_{SS} pins (see 2.2 Power Supply Pins)
- $\overline{\text{MCLR}}$ pin (see 2.3 Master Clear (MCLR) Pin)

These pins must also be connected if they are being used in the end application:

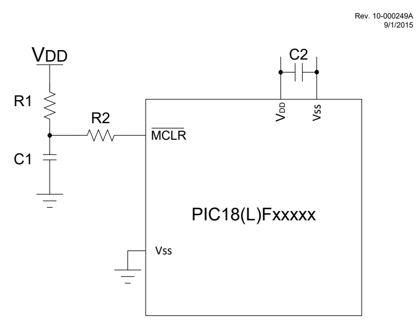
- ICSPCLK/ICSPDAT pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see 2.4 In-Circuit Serial Programming™ ICSP™ Pins)
- OSCI and OSCO pins when an external oscillator source is used (see 2.5 External Oscillator Pins)

Additionally, the following pins may be required:

- V_{REF}+/V_{REF}- pins are used when external voltage reference for analog modules is implemented

The minimum mandatory connections are shown in the figure below.

Figure 2-1. Recommended Minimum Connections



Key (all values are recommendations):
C1 and C2 : 0.1 µF, 20V ceramic
R1: 10 kΩ
R2: 100Ω to 470Ω

2.2 Power Supply Pins

2.2.1 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins (V_{DD} and V_{SS}) is required.

Consider the following criteria when using decoupling capacitors:

- Value and type of capacitor: A 0.1 μF (100 nF), 10-20V capacitor is recommended. The capacitor should be a low-ESR device, with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- Placement on the printed circuit board: The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the

device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).

- Handling high-frequency noise: If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μF in parallel with 0.001 μF).
- Maximizing performance: On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 Tank Capacitors

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits, including microcontrollers, to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μF to 47 μF.

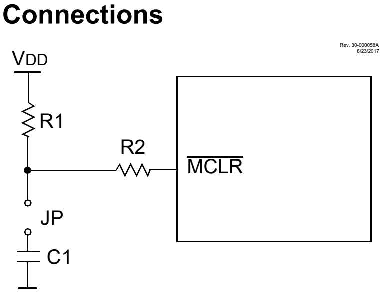
2.3 Master Clear ($\overline{MCLR}$) Pin

The $\overline{MCLR}$ pin provides two specific device functions: Device Reset, and Device Programming and Debugging. If programming and debugging are not required in the end application, a direct connection to V_{DD} may be all that is required. The addition of other components, to help increase the application's resistance to spurious Resets from voltage sags, may be beneficial. A typical configuration is shown in Figure 2-1. Other circuit designs may be implemented, depending on the application's requirements.

During programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{MCLR}$ pin. Consequently, specific voltage levels (V_{IH} and V_{IL}) and fast signal transitions must not be adversely affected. Therefore, specific values of R1 and C1 will need to be adjusted based on the application and PCB requirements. For example, it is recommended that the capacitor, C1, be isolated from the $\overline{MCLR}$ pin during programming and debugging operations by using a jumper (Figure 2-2). The jumper is replaced for normal run-time operations.

Any components associated with the $\overline{MCLR}$ pin should be placed within 0.25 inch (6 mm) of the pin.

Figure 2-2. Example of $\overline{MCLR}$ Pin Connections



Note:

1. R1 ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{MCLR}$ pin V_{IH} and V_{IL} specifications are met.
2. R2 ≤ 470Ω will limit any current flowing into $\overline{MCLR}$ from the extended capacitor, C1, in the event of $\overline{MCLR}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{MCLR}$ pin V_{IH} and V_{IL} specifications are met.

2.4 In-Circuit Serial Programming™ ICSP™ Pins

The ICSPCLK and ICSPDAT pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of ohms, not to exceed 100Ω.

Pull-up resistors, series diodes and capacitors on the ICSPCLK and ICSPDAT pins are not recommended as they can interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits, and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

For device emulation, ensure that the “Communication Channel Select” (i.e., ICSPCLK/ICSPDAT pins), programmed into the device, matches the physical connections for the ICSP to the Microchip debugger/ emulator tool.

For more information on available Microchip development tools connection requirements, refer to the *“Development Support”* section.

Related Links

37. Development Support

2.5 External Oscillator Pins

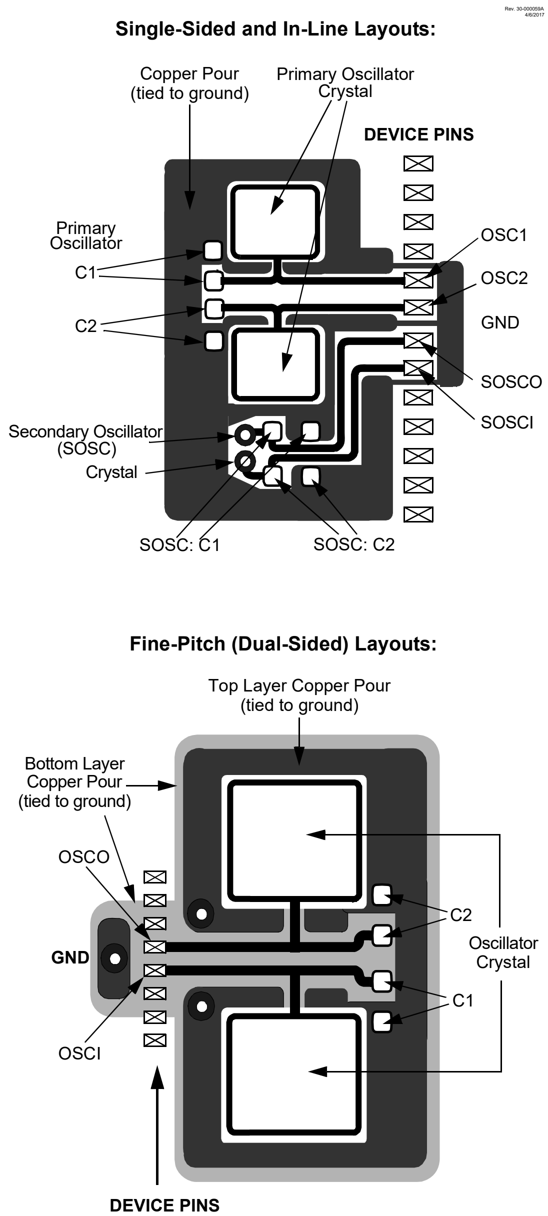
Many microcontrollers have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator.

The oscillator circuit should be placed on the same side of the board as the device. Place the oscillator circuit close to the respective oscillator pins with no more than 0.5 inch (12 mm) between the circuit components and the pins. The load capacitors should be placed next to the oscillator itself, on the same side of the board.

Use a grounded copper pour around the oscillator circuit to isolate it from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed.

Layout suggestions are shown in the following figure. In-line packages may be handled with a single-sided layout that completely encompasses the oscillator pins. With fine-pitch packages, it is not always possible to completely surround the pins and components. A suitable solution is to tie the broken guard sections to a mirrored ground layer. In all cases, the guard trace(s) must be returned to ground.

Figure 2-3. Suggested Placement of the Oscillator Circuit



In planning the application's routing and I/O assignments, ensure that adjacent port pins, and other signals in close proximity to the oscillator, are benign (i.e., free of high frequencies, short rise and fall times, and other similar noise).

For additional information and design guidance on oscillator circuits, refer to these Microchip Application Notes, available at the corporate website (www.microchip.com):

- AN826, *"Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices"*
- AN849, *"Basic PICmicro® Oscillator Design"*
- AN943, *"Practical PICmicro® Oscillator Analysis and Design"*
- AN949, *"Making Your Oscillator Work"*

Related Links

4. Oscillator Module (with Fail-Safe Clock Monitor)

2.6 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state. Alternatively, connect a 1 kΩ to 10 kΩ resistor to V_{SS} on unused pins to drive the output to logic low.

3. Device Configuration

Device configuration consists of Configuration Words, Code Protection, Device ID and Rev ID.

3.1 Configuration Words

There are six Configuration Words that allow the user to select the device oscillator, reset, and memory protection options. These are implemented as Configuration Word 1 through Configuration Word 6 at 300000h through 30000Bh.

Important: The $\overline{\text{DEBUG}}$ bit in Configuration Words is managed automatically by device development tools including debuggers and programmers. For normal device operation, this bit should be maintained as a '1'.

3.2 Code Protection

Code protection allows the device to be protected from unauthorized access. Program memory protection and data memory protection are controlled independently. Internal access to the program memory is unaffected by any code protection setting.

3.2.1 Program Memory Protection

The entire program memory space is protected from external reads and writes by the $\overline{\text{CP}}$ bit. When $\overline{\text{CP}}$ = 0, external reads and writes of program memory are inhibited and a read will return all '0's. The CPU can continue to read program memory, regardless of the protection bit settings. Self-writing the program memory is dependent upon the write protection setting.

3.2.2 Data Memory Protection

The entire Data EEPROM Memory space is protected from external reads and writes by the $\overline{\text{CPD}}$ bit. When $\overline{\text{CPD}}$ = 0, external reads and writes of Data EEPROM Memory are inhibited and a read will return all '0's. The CPU can continue to read Data EEPROM Memory regardless of the protection bit settings.

3.3 Write Protection

Write protection allows the device to be protected from unintended self-writes. Applications, such as boot loader software, can be protected while allowing other regions of the program memory to be modified.

The WRT bits define the size of the program memory block that is protected.

3.4 User ID

256 bytes in the memory space (200000h-20000FFh) are designated as ID locations where the user can store checksum or other code identification numbers. These locations are readable and writable during normal execution. See the *"User ID, Device ID and Configuration Word Access"* section for more information on accessing these memory locations. For more information on checksum calculation, see the *"PIC18F24/25Q10 Memory Programming Specification"*, (DS40001874).

3.5 Device ID and Revision ID

The 16-bit device ID word is located at 0x3FFFFE and the 16-bit revision ID is located at 0x3FFFFC. These locations are read-only and cannot be erased or modified.

Development tools, such as device programmers and debuggers, may be used to read the Device ID, Revision ID and Configuration Words. Refer to the *“Nonvolatile Memory (NVM) Control”* section for more information on accessing these locations.

Related Links

11. (NVM) Nonvolatile Memory Control